

RELIABILITY REPORT
FOR
MAX6734KALTD3+T
PLASTIC ENCAPSULATED DEVICES

September 8, 2011

MAXIM INTEGRATED PRODUCTS

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Conclusion

The MAX6734KALTD3+T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX6730-MAX6735 single-/dual-/triple-voltage microprocessor (μP) supervisors feature a watchdog timer and manual reset capability. The MAX6730-MAX6735 offer factory-set reset thresholds for monitoring voltages from +0.9V to +5V and an adjustable reset input for monitoring voltages down to +0.63V. The combination of these features significantly improves system reliability and accuracy when compared to separate ICs or discrete components. The active-low reset output asserts and remains asserted for the reset timeout period after all the monitored voltages exceed their respective thresholds. Multiple factory-set reset threshold combinations reduce the number of external components required. The MAX6730/MAX6731 monitor a single fixed voltage, the MAX6732/MAX6733 monitor two fixed voltages, and the MAX6734/MAX6735 monitor two fixed voltages and one adjustable voltage. All devices are offered with six minimum reset timeout periods ranging from 1.1ms to 1120ms. The MAX6730-MAX6735 feature a watchdog timer with an independent watchdog output. The watchdog timer prevents system lockup during code execution errors. A watchdog startup delay of 54s after reset asserts allows system initialization during power-up. The watchdog operates in normal mode with a 1.68s delay after initialization. The MAX6730/MAX6732/MAX6734 provide an active-low, open-drain watchdog output. The MAX6731/MAX6733/MAX6735 provide an active-low, push-pull watchdog output. Other features include a manual reset input (MAX6730/MAX6731/MAX6734/MAX6735) and push-pull reset output (MAX6731/MAX6733/MAX6735) or open-drain reset output (MAX6730/MAX6732/MAX6734). The MAX6730-MAX6733 are offered in a tiny SOT23-6 package. The MAX6734/MAX6735 are offered in a space-saving SOT23-8 package. All devices are fully specified over the extended -40°C to $+85^{\circ}\text{C}$ temperature range.

II. Manufacturing Information

A. Description/Function:	Single-/Dual-/Triple-Voltage μ P Supervisory Circuits with Independent Watchdog Output
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand
F. Date of Initial Production:	July 22, 2006

III. Packaging Information

A. Package Type:	8L SOT23
B. Lead Frame:	NiPdAu
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1601-0170 / C
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	N/A
K. Single Layer Theta Jc:	80°C/W
L. Multi Layer Theta Ja:	180°C/W
M. Multi Layer Theta Jc:	60°C/W

IV. Die Information

A. Dimensions:	32 X 57 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 133 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 8.3 \times 10^{-9}$$

$$\lambda = 8.3 \text{ F.I.T. (60\% confidence level @ 25}^\circ\text{C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot J7I6EA013B D/C 1113)

The MS69-6 die type has been found to have all pins able to withstand a transient pulse of:

ESD-HBM:	+/- 2500V per JEDEC JESD22-A114
ESD-CDM:	+/- 750V per JEDEC JESD22-C101

Latch-Up testing has shown that this device withstands a current of +/-100mA and overvoltage per JEDEC JESD78.

Table 1
Reliability Evaluation Test Results

MAX6734KALTD3+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	44	0	T0000Q053B, D/C 0614
	Biased	& functionality	44	0	S716CQ001B, D/C 0452
	Time = 192 hrs.		45	0	S0000U001A, D/C 0529

Note 1: Life Test Data may represent plastic DIP qualification lots.